



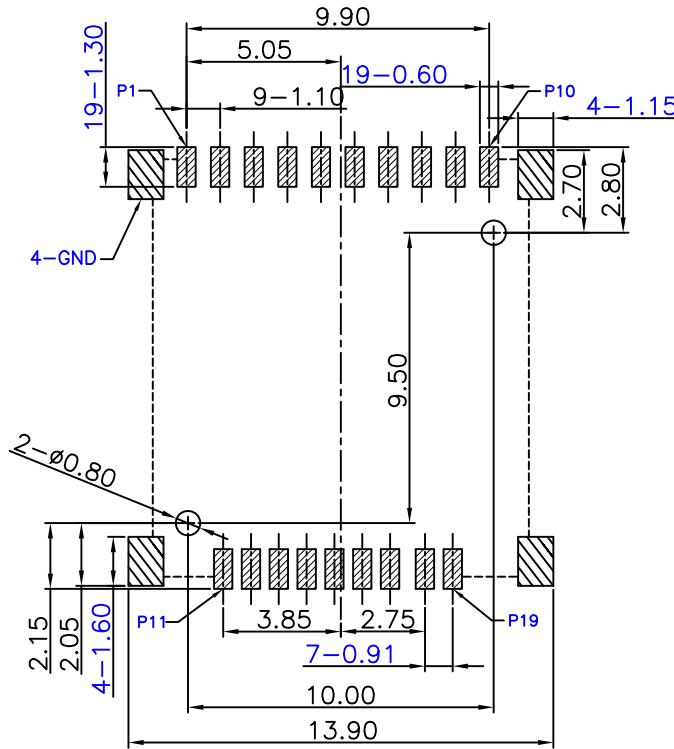
**Operating Force**

Inward 3.0~5.0N. (1N.=100gram-force)  
 Exiting 3.0~5.0N. (1N.=100gram-force)

**Solder-ability (Max.)**

IR Reflow: 255°C, 5sec. Manual: 350°C, 3sec.

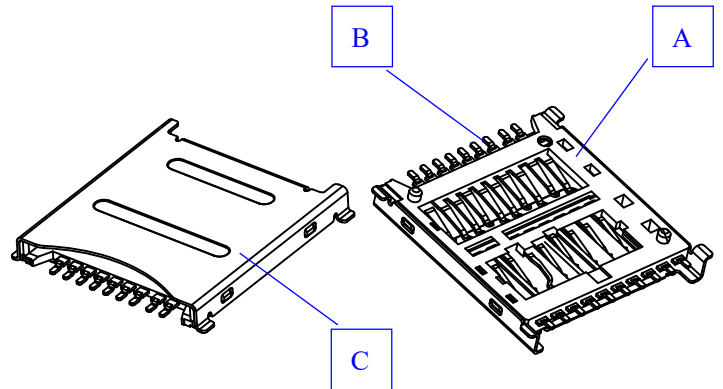
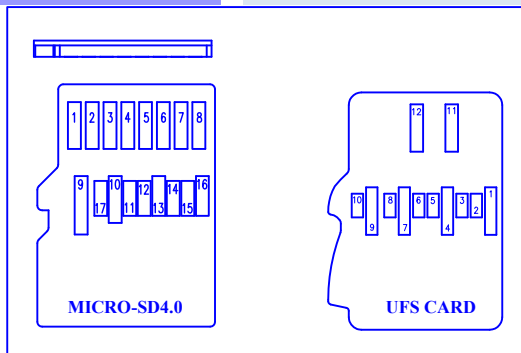
- PAD AREA
- KEEP OUT AREA
- GND PATTERN ONLY



DECIMALS	ANGLES
X : ±0.35	X° : ±3°
X.X : ±0.20	X.X° : ±1°
X.XX : ±0.10	X.XX° : ±0.5°

CARD

MICRO-SD4.0 / UFS CARD



Material declaration

	NAME	MATERIAL	PLATING
<b>A</b>	基体 HOUSING	LCP(S475) 30%G/F (Black)耐热塑胶 UL 94V-0	SET
<b>B</b>	接触端子 CONTACT	C5210R-H (t=0.15mm)磷铜 【Au G/F PLATING OVER Ni】 SOLDER TAIL AREA:MATTE TIN 80~100u" OVER Ni	G/F
<b>C</b>	外壳 SHELL	SUS304(t=0.20mm)不锈钢 SOLDER ABLE AREA 【Ni PLATING OVER ALL】	-

本品不屬於危害性廢棄物,須丟棄時可以委託回收商予以回收再生處理。Products do not belong to hazardous waste, When waste can recycling processing

運送時本產品不要直接與水、酸鹼性化學物質接觸,或放置於含有以上氣體環境中,並且需要注意會有滑落、側翻的危險發生; 運輸過程中不能有碰撞或者擠壓,須保證溫度與濕度適中 [常溫 25°C, 濕度在 50°C 以內], 不可導致材料變形或氧化。

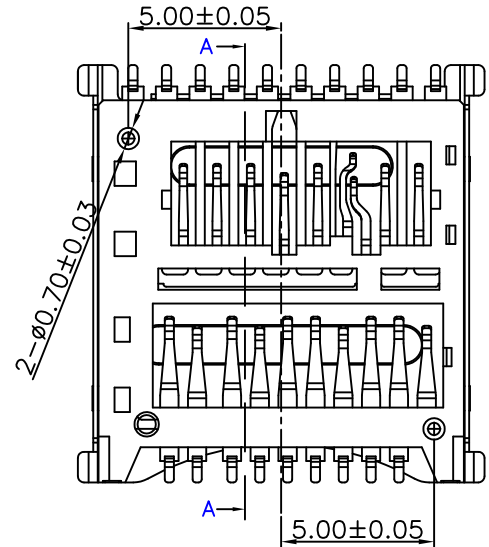
注記 NOTICE

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## Pin define

Pin No.	microSD	UFS	UHS-II microSD
P1	VSS	VSS	VSS
P2	8-DAT1		8-RCLK-
P3	7-DAT0		7-RCLK+
P4	6-CD	11-CD	6-CD
P5	5-CLK		5-Not used
P6	4-VDD	12-VCC	4-VDD1(3.3V)
P7	3-CMD		3-Not used
P8	2-DAT3		2-Not used
P9	1-DAT2		1-Not used
P10	VSS	1-VSS	16-VSS
P11		2-DIN_C	15-D1+
P12		3-DIN_T	14-D1-
P13		4-VSS	13-VSS
P14		5-DOUT_C	12-D0-
P15		6-DOUT_T	11-D0+
P16		7-VSS	10-VSS
P17		8-REF_CLK	
P18		9-VCCQ2	9-VDD2(1.8V)
P19	VSS	10-VSS	VSS

## BOTTOM-VIEW



### 手焊接时

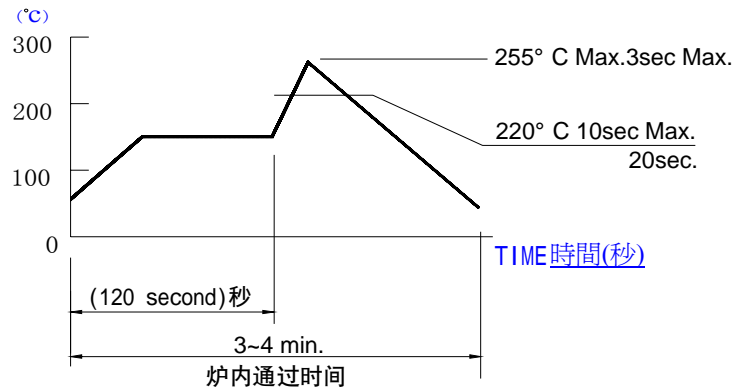
项目	条件
焊接温度	350°C max.
连续焊接时间	3s max.
焊剂斗容量	60W max.

Please practice according to below condition:

- (1) Preheat : 150 °C 90-120s
- (2) Soldering heat : 260 °C Max 10S.
- (3) Immersion depth: Up to the surface of the board

### 自动浸焊时

项目	条件
助焊剂附着量	不附着于零部件贴装面的程度
预热温度	印刷电路板焊接面的周围温度 100°C max.
预热温度时间	60s max.
焊接温度	255°C max.
焊接浸渍时间	5s max.
焊接次数	2次以下



## CARRIER TAPE

